



AF/2800

Attorney Docket SEL 173  
*#144/Amend C 6/1/02 Anom 4/1/02*IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of

Ohtani et al.

Serial No.: 09/535,836

Filed: March 28, 2000

For: Semiconductor Device Having  
Multi-layer Wiring

Art Unit: 2811

Examiner: H. Vu

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on March 7, 2002

Rachelle Hamnerquist  
Rachelle Hamnerquist 3702  
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Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT C (AFTER FINAL)

Sir:

In response to the Final Rejection dated January 7, 2002, please enter the following amendment in the above-identified application.

IN THE CLAIMS:

Please amend the claims as follows:

41. (Amended) The semiconductor device according to claim 40, wherein said first wiring is selected from the group consisting of aluminum and a material predominantly composed of aluminum.

42. (Amended) The semiconductor device according to claim 40, wherein said second wiring is selected from the group consisting of titanium and a material predominantly composed of titanium.